



Patent
111818-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Benham Malekkhosravi, et al.

Serial No. 10/789,066

Filed: February 27, 2004

For: METHOD AND ARCHITECTURE
FOR INTEGRATED CIRCUIT
DESIGN AND MANUFACTURE

)
) **Group Art Unit:** 2825

)
) **Examiner:** To be assigned

PRELIMINARY AMENDMENT UNDER 37 C.F.R. §1.115

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant respectfully requests entry of the following amendments to the above-captioned application before examination of this case:

Amendment to the Claims

In the Claims:

1. (recited) A system for integrated circuit (IC) design comprising:
at least one structural multi-project wafer (SMPW) comprising a plurality of pre-manufactured and pre-validated functional blocks; and
a streamlined IC design flow incorporating the SMPW and having no IP integration or floor planning requirements.

CERTIFICATE OF MAILING
(37 C.F.R. §1.8)

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as 'First Class Mail' in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 21, 2004
Date of Deposit
111818.000001/490702.01

Karen M. Cruz
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